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National Phase Entry of PCT/JP03/08194

Confirmation No.:

Date:

APPLICATION DATA SHEET**Applicant Information**

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Correspondence Information

Correspondence Customer Number:: 06449

Application Information

Title Line One:: Method of forming dielectric filler-
Title Line Two:: containing polyimide coating on metallic
Title Line Three:: material, method of manufacturing copper
Title Line Four:: clad laminate for forming capacitor layer
Title Line Five:: for use in printed wiring board, and
Title Line Six:: copper clad laminate obtained through the
Title Line Seven:: manufacturing method
Total Drawing Sheets:: 3
Formal Drawings?:: Yes
Application Type:: Utility
Docket Number:: 2922-482

Secrecy Order in Parent Appl?:: No

Representative Information

Representative Customer Number:: The practitioners associated
Representative Customer Number:: with customer number 06449

Domestic Priority Information

This application is a:: 371
>Application One:: PCT/JP03/08194
Filing Date:: June 27, 2003
Patent Number::

Foreign Priority Information

Foreign Application One:: 2002-191517
Filing Date:: June 28, 2002
Country:: Japan
Priority Claimed:: Yes

Assignment Information

Assignee name:: Mitsui Mining & Smelting Co., Ltd.
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